

2SD1263, 2SD1263A

Silicon NPN triple diffusion planar type

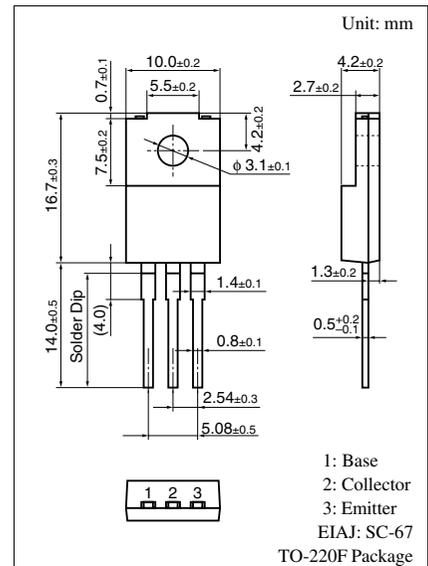
For power amplification

■ Features

- High collector to base voltage V_{CBO}
- Full-pack package which can be installed to the heat sink with one screw

■ Absolute Maximum Ratings $T_C = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector to base voltage	2SD1263	350	V
	2SD1263A	400	
Collector to emitter voltage	2SD1263	250	V
	2SD1263A	300	
Emitter to base voltage	V_{EBO}	5	V
Peak collector current	I_{CP}	1.5	A
Collector current	I_C	0.75	A
Collector power dissipation	$T_C = 25^\circ\text{C}$	35	W
	$T_a = 25^\circ\text{C}$	2	
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

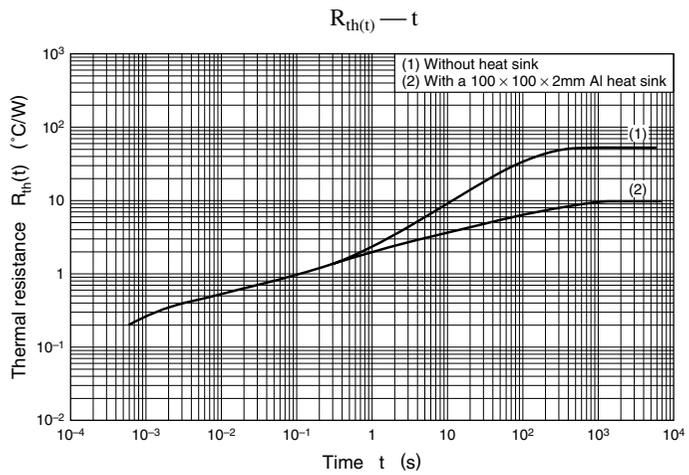
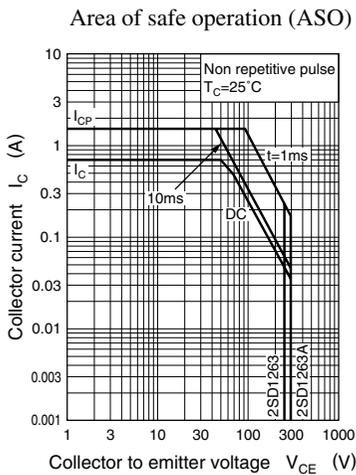
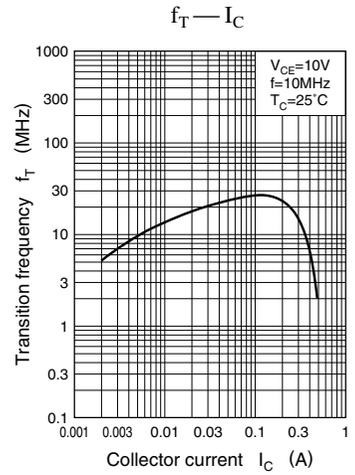
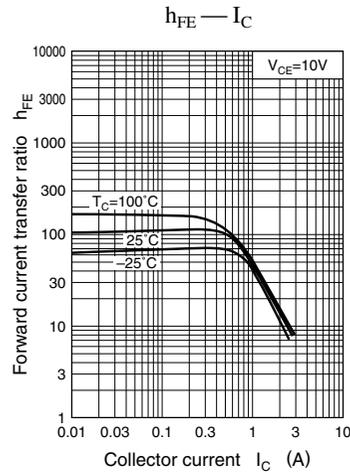
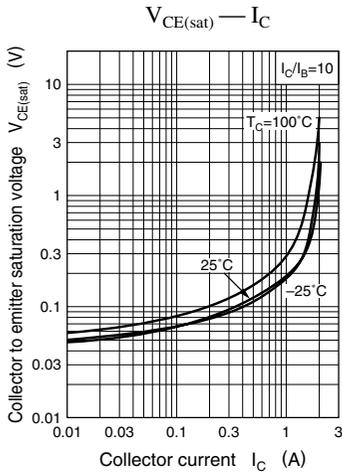
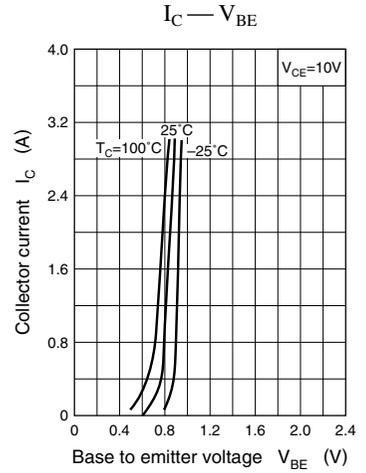
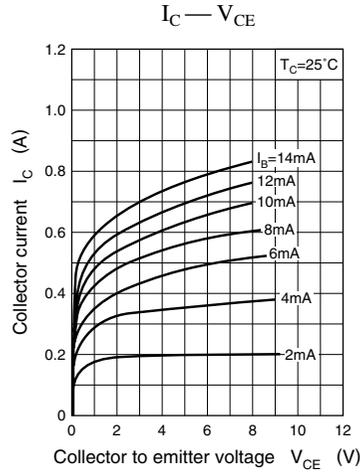
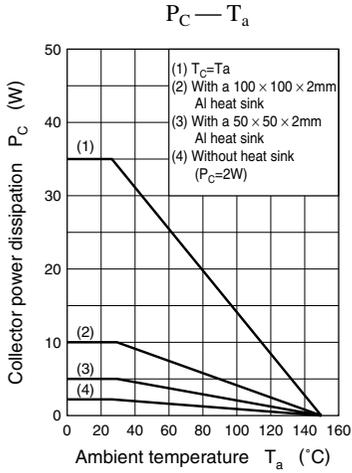


■ Electrical Characteristics $T_C = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector cutoff current	2SD1263	$V_{CE} = 350\text{ V}, V_{BE} = 0$			1	mA
	2SD1263A					
Collector cutoff current	2SD1263	$V_{CE} = 150\text{ V}, I_B = 0$			1	mA
	2SD1263A					
Emitter cutoff current	I_{EBO}	$V_{EB} = 5\text{ V}, I_C = 0$			1	mA
Collector to emitter voltage	2SD1263	$I_C = 30\text{ mA}, I_B = 0$	250			V
	2SD1263A					
Forward current transfer ratio	h_{FE1}^*	$V_{CE} = 10\text{ V}, I_C = 0.3\text{ A}$	70		250	
	h_{FE2}	$V_{CE} = 10\text{ V}, I_C = 1\text{ A}$	10			
Base to emitter voltage	V_{BE}	$V_{CE} = 10\text{ V}, I_C = 1\text{ A}$			1.5	V
Collector to emitter saturation voltage	$V_{CE(sat)}$	$I_C = 1\text{ A}, I_B = 0.2\text{ A}$			1	V
Transition frequency	f_T	$V_{CE} = 5\text{ V}, I_C = 0.5\text{ A}, f = 10\text{ MHz}$		30		MHz
Turn-on time	t_{on}	$I_C = 1\text{ A}, I_{B1} = 0.1\text{ A}, I_{B2} = -0.1\text{ A}, V_{CC} = 50\text{ V}$		0.5		μs
Storage time	t_{stg}		2		μs	
Fall time	t_f		0.5		μs	

Note) *: Rank classification

Rank	Q	P
h_{FE1}	70 to 150	120 to 250



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